
TPS653850-Q1 Multirail Power Supply for Microcontrollers in Safety-Relevant Applications

1 Device Overview

1.1 Features

- Qualified for Automotive Applications
- AEC-Q100 Qualified With the Following Results:
 - Device Temperature Grade 1: –40°C to +125°C Ambient Operating Temperature
 - Device HBM ESD Classification Level 2
 - Device CDM ESD Classification Level C4B
- Input Voltage Range
 - 7 to 36 V for Initial Battery Power Up
 - 3.8- to 36-V Full Functionality After Initial Battery Power Up
 - Minimum 2.3 V During Operation After Wake-up
- Supply Rails
 - 6-V Synchronous Buck-Boost Preregulator With Internal FETs
 - 5-V, 200-mA (CAN) LDO With Internal FET
 - 3.3-V or 5-V, 350-mA (MCU IO) LDO With Internal FET
 - 2 Sensor Supply LDOs With Internal FETs
 - 120 mA for Sensor Supply 1, 20 mA for Sensor Supply 2
 - Configurable Tracking Mode (Tracking Input Pin), or 3.3-V or 5-V Fixed Output Voltage
 - Short-to-Ground and Battery Protection
 - Charge Pump: 6-V Minimum, 11-V Maximum Above Battery Voltage
- Monitoring and Protection
 - Independent Undervoltage and Overvoltage Monitoring on All Regulator Outputs, Battery Voltage, and Internal Supplies
 - Voltage Monitoring Circuitry, Including Independent Bandgap Reference, Supplied from Separate Battery Voltage Input Pin
 - Self-Check on All Voltage Monitoring (During Power-Up and After Power-Up Initiated by External MCU)
 - All Supplies Protected With Current Limit and Overtemperature Prewarning and Shutdown
- Microcontroller Interface
 - Open and Close Window or Question-Answer Watchdog Function
 - Lock-Step MCU Error-Signal Monitor
 - DIAGNOSTIC state for Performing Device Self-Tests and System Diagnostics
 - SAFE State for Device and System Protection upon Detected System Failure
 - Clock Monitor for Internal Oscillator
 - Analog and Logic Built-In Self-Test
 - CRC on Non-Volatile Memory as well as Device and System Configuration Registers and SPI Communications
 - Reset Circuit for MCU
 - Diagnostic Output Pin
- SPI With CRC on Command Plus Data
- Error Reporting Through SPI Registers for Errors on System Level and Device Level
- Enable-Drive Output for Disabling External Power-Stages on Any Detected System Failure
- Wake-up through IGNITION Pin or CAN WAKUP Pin
- 48-Pin HTSSOP PowerPAD™ IC Package

1.2 Applications

- Safety-Relevant Automotive Applications
- Industrial Safety-Relevant Applications

1.3 Description

The TPS653850-Q1 device is a multirail power supply designed to supply microcontrollers in safety relevant applications, such as those found in the automotive industry. The device supports microcontrollers with dual-core lockstep (LS) or loosely coupled architectures (LC).



The TPS653850-Q1 device integrates multiple supply rails to power the MCU, CAN or FlexRay, and external sensors. A buck-boost converter with internal FETs converts the input battery voltage between 2.3 V and 36 V to a 6-V preregulator output that supplies the other regulators. An integrated charge pump provides an overdrive voltage for the internal regulators, and can also be used to drive an external NMOS FET as reverse battery protection. The device supports wake-up from an ignition (IGN) signal or wake-up from a CAN transceiver signal.

An independent voltage monitoring unit inside the device monitors undervoltage and overvoltage on all internal supply rails and regulator outputs of the battery supply. Regulator current limits and temperature protections are also implemented. The TPS653850-Q1 device features a question-answer watchdog, MCU error-signal monitor, clock monitoring on internal oscillator, self-check on clock monitor, cyclic redundancy check (CRC) on non-volatile memory and SPI communication, a diagnostic output pin allowing MCU to observe device internal analog and digital signals, a reset circuit for the MCU and an enable output to disable external power-stages on any detected system-failure. A built-in self-test (BIST) allows for monitoring the device functionality at start-up. A dedicated DIAGNOSTIC state allows the MCU to check TPS653850-Q1 functionality.

The TPS653850-Q1 device also has an error reporting capability through the SPI register. The device has separate status bits in the SPI register for each specific error on the system level or device level. When the device detects a particular error condition, it sets the appropriate status bit and keeps this status bit set until the MCU reads-out the SPI register in which this status bit was set. Based on which status bit was set, the MCU can decide whether it must keep the system in a safe state or whether it can resume with the operation of the system.

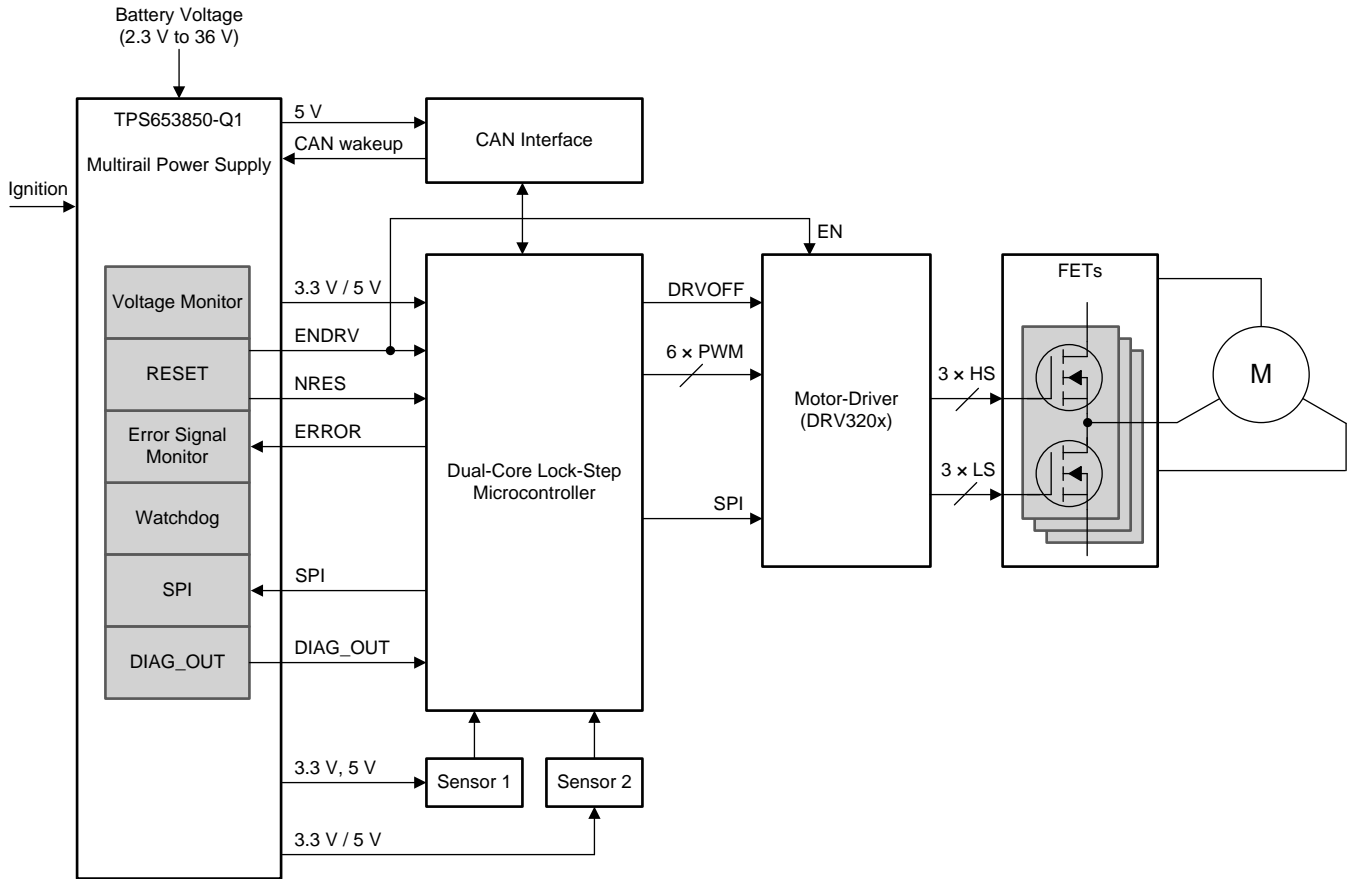
The TPS653850-Q1 device is available in a 48-pin HTSSOP PowerPAD IC package.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE
TPS653850-Q1	HTSSOP (48)	12.50 mm x 6.10 mm

(1) For more information, see [Section 3](#), *Mechanical Packaging and Orderable Information*.

1.4 Typical Application Diagram



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Figure 1-1. Typical Application Diagram

2 Device and Documentation Support

2.1 Documentation Support

2.1.1 Related Documentation

For related documentation see the following:

- [DRV3201-Q1 3 Phase Motor Driver-IC for Automotive Safety Applications](#) (SLVSBD6)
- [DRV3205-Q1 Three-Phase Automotive Gate Driver With Three Integrated Current Shunt Amplifiers and Enhanced Protection, Diagnostics, and Monitoring](#) (SLVSCV1)

2.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

2.3 Community Resources

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TI E2E™ Online Community The TI engineer-to-engineer (E2E) community was created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support TI's Design Support Quickly find helpful E2E forums along with design support tools and contact information for technical support.

2.4 Trademarks

PowerPAD, E2E are trademarks of Texas Instruments.
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2.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

2.6 Glossary

TI Glossary This glossary lists and explains terms, acronyms, and definitions.

3 Mechanical Packaging and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
O3850QDCARQ1	PREVIEW	HTSSOP	DCA	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	O3850	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

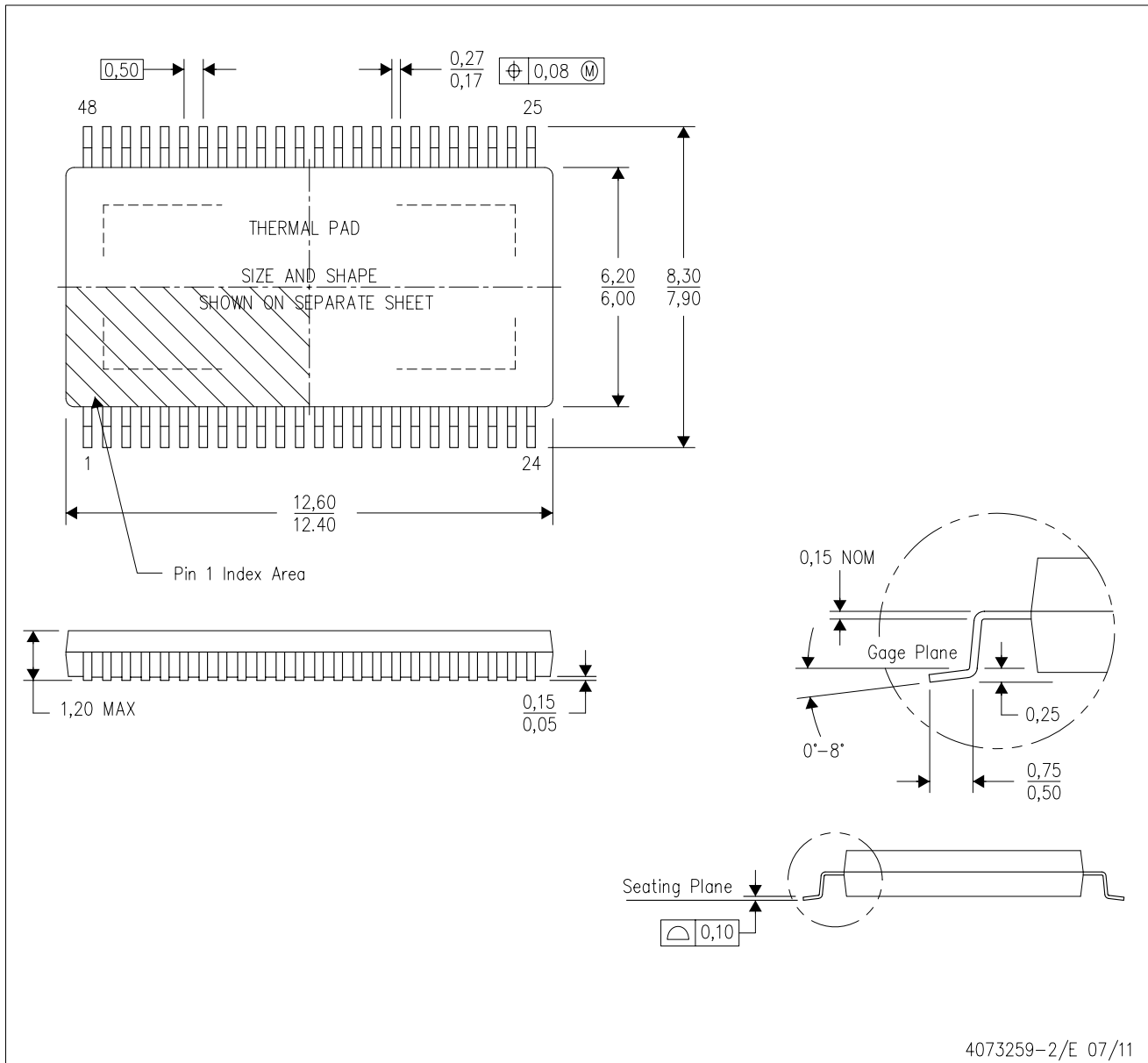
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MECHANICAL DATA

DCA (R-PDSO-G48)

PowerPAD™ PLASTIC SMALL-OUTLINE



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - Falls within JEDEC MO-153

PowerPAD is a trademark of Texas Instruments.

THERMAL PAD MECHANICAL DATA

DCA (R-PDSO-G48)

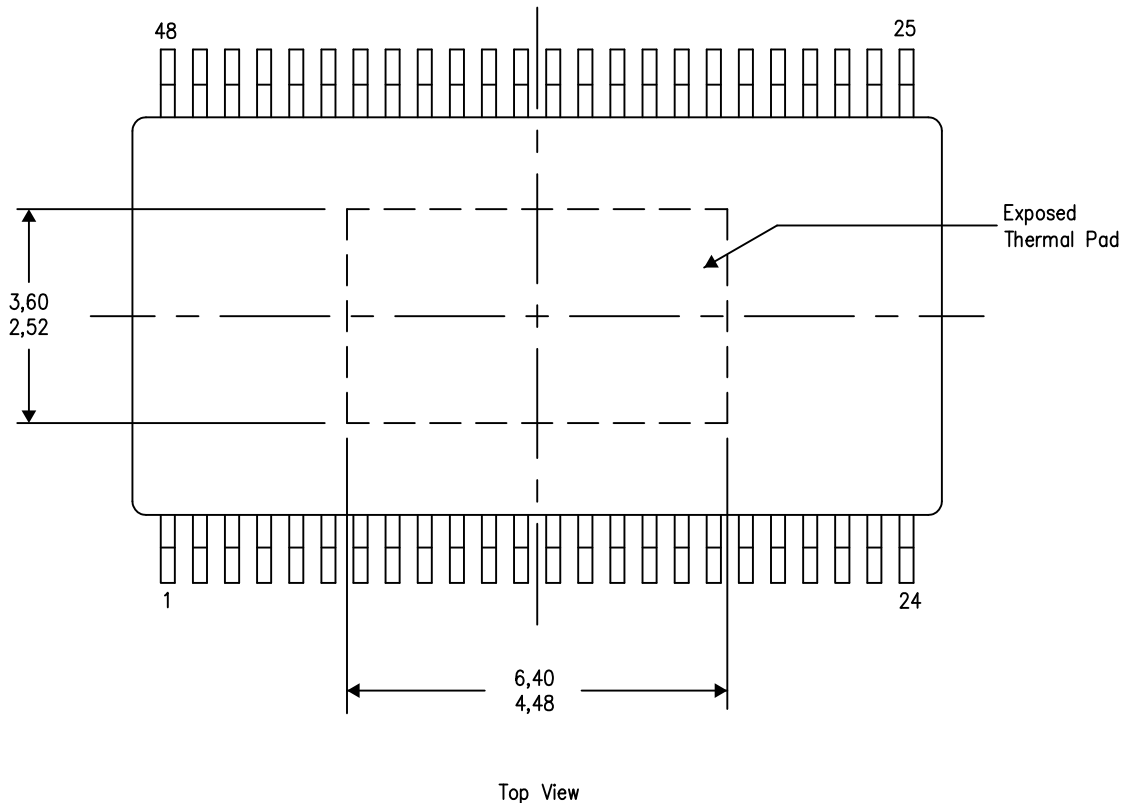
PowerPAD™ PLASTIC SMALL OUTLINE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

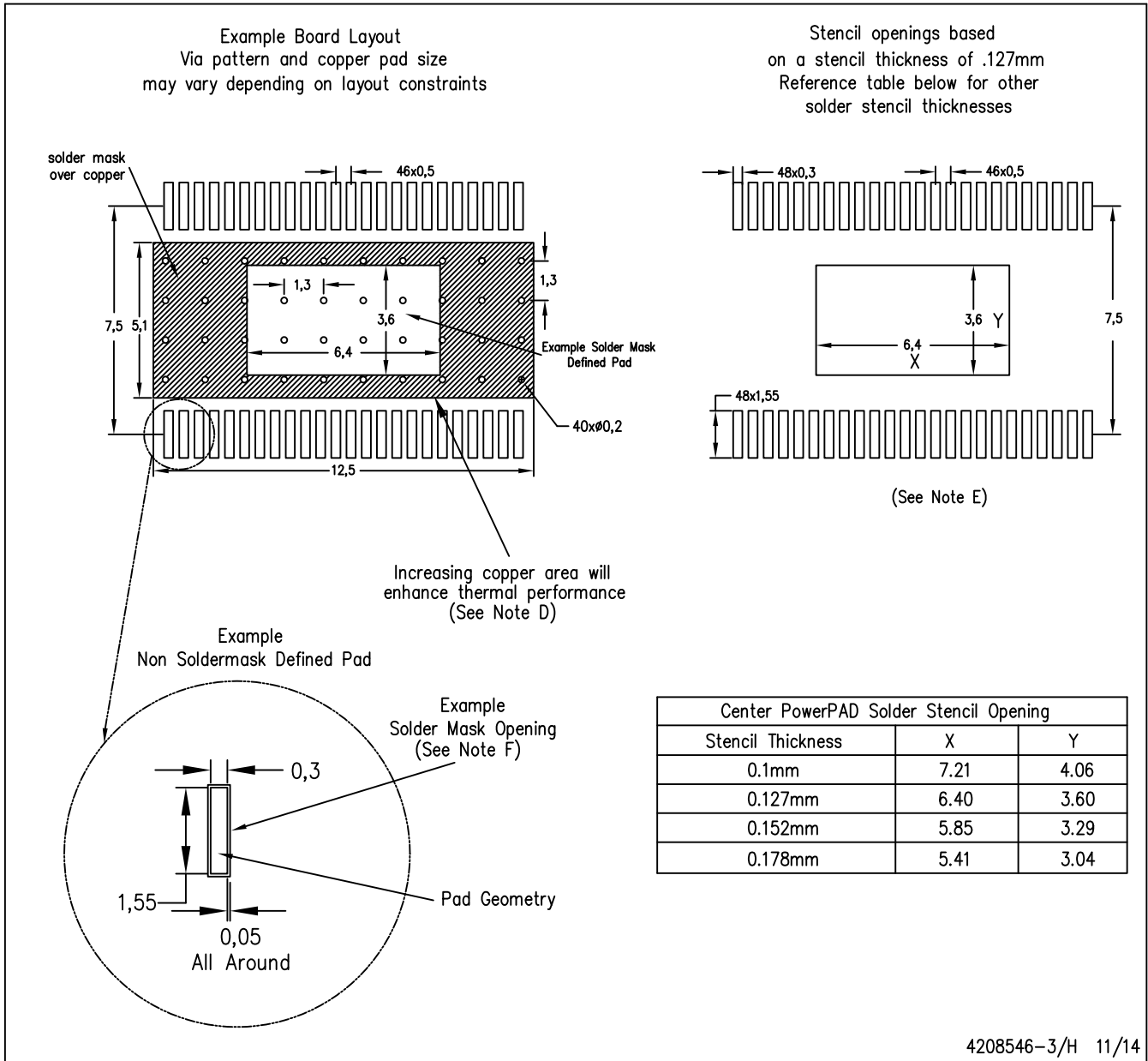


Exposed Thermal Pad Dimensions

4206320-4/S 11/14

NOTE: A. All linear dimensions are in millimeters

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4208546-3/H 11/14

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
 - F. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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